

# CONTROL SIGNAL TRANSMITTING METHOD WITH PACKAGE POWER PIN AND RELATED INTEGRATED CIRCUIT PACKAGE STRUCTURE

## ABSTRACT OF THE DISCLOSURE

5           A method and a device are disclosed for transmitting a control signal to an option  
pad of an integrated circuit chip at its package level. The method includes the steps of:  
electrically isolating one of a plurality of commonly connected power transmitting pins of  
the integrated circuit package; connecting the electrically isolated power transmitting pin  
to the option pad to thereby transmit a control signal from outside through the electrically  
10       isolated power transmitting pin to the option pad.